#### 504393410 06/01/2017

# PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT

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### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	15532349	

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DATE SIGNED:	06/01/2017

**Total Attachments: 1** 

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**PATENT** 504393410

REEL: 042663 FRAME: 0962

## ASSIGNMENT

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(1) Lee Keon Hwa	<u></u>	(4)	
(2) Choi. Bycong K	YUR	(5)	<i></i>
(3)		(6)	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
who have made a certain new	and useful invention, hereby sell, sesign and tra	water unto	
	LG INNOTEK		
	98, Huam-ro, Jung-gu, Seoul	34637 Republic	of Korea
its successors and assigns (he 35 U.S.C. 100 in the invention	reinafter designated "ASSIGNEE") the entire $\epsilon$ a entitled	ight, title and interest for	the United States of America as defined in
LIGHT E	MITTING DIODE AND LIG COMPRISIN		G DIODE ARRAY
(a) for which an application Sected No.	for United States Letters Patent was filed on		, and identified by United States
(b) for which an application	for United States Letters Patent was essecuted c	May 24, 2017	; May 26, 2017
and the undersigned hereby a Letters Patent which may b senervals, continuations, or o Convention for the Protection	suthorise and request the United States Commit e granted therefor and/or that claim priority outinustions-in-part thereof and/or that claim to of Industrial Property to the said ASSIGN ted agree that the attorneys of record in said ap	ssioner of Patents and Tx thereto and any and all priority thereto, and the EE, for its interest as Ai	ademarks to issue any and all United States extensions, divisions, reissues, substitutes, right to all benefits under the International ELGNEE, its successors, assigns and legal
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SIGNED on the dates indica	ited salde our signatures:		
INVENTOR			DATE SIGNED
n Name: Lee, Keon	Hwa	ood (1.84°)	\$124/2019
a Name: Oloi, Byo	M ong Kyun	*******	4/26/2017
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